



**TYPICAL APPLICATION**

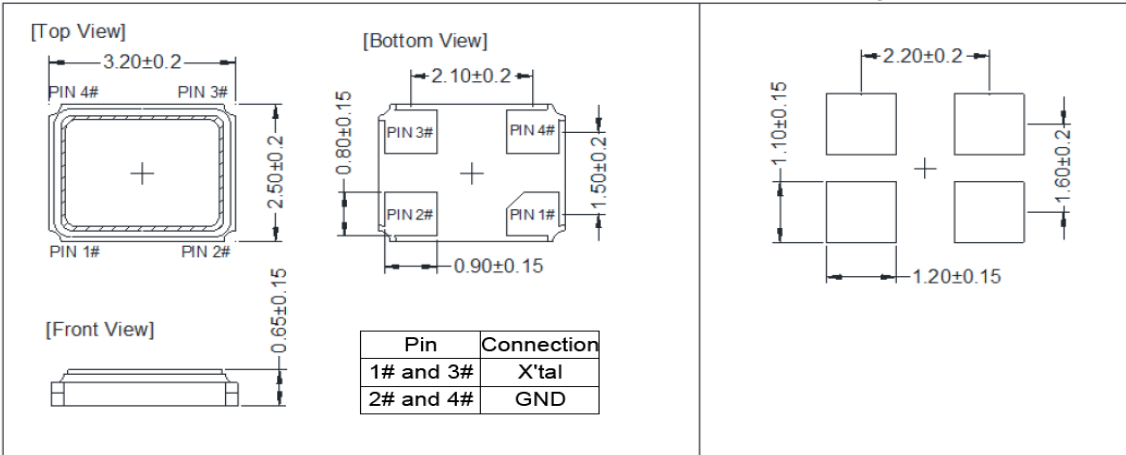
- Bluetooth, Mobile Phone, GPS
- Wireless LAN, 4G/LTE
- Hard Disk



**DIMENSIONS (mm)**

Product Dimensions

Solder Pad Layout Dimensions



**ELECTRICAL SPECIFICATION**

PARAMETERS	XMD-SMD3225			UNITS	CONDITIONS
	MIN	TYP	MAX		
Nominal Frequency	8		54	MHz	-
Mode of vibration	Fundamental				-
Frequency Tolerance	10 20 30 or specify			ppm	@+25°C±3°C
Frequency Stability	Table 2			ppm	Ref 25°C±3°C
Load Capacitance	8pF 10pF or specify			pF	-
Shunt Capacitance			2	pF	@+25°C±3°C
Equivalent Series Resistance	Table 1			Ω	-
Drive Level		10	200	μW	-
Operating Temperature Range	-40		125	°C	-
Storage Temperature	-55		125	°C	-
Aging (First Year)	-3		3	ppm	-
Insulation Resistan	500			MΩ	@DC100V

**EQUIVALENT SERIES RESISTANCE (Table 1)**

Frequency Range	MODE	E.S.R(Ω)
8MHz ≤ F0 ≤ 10MHz	Fundamental	200
10MHz < F0 < 16MHz	Fundamental	100
16MHz ≤ F0 ≤ 20MHz	Fundamental	60
20MHz < F0 ≤ 32MHz	Fundamental	40
32MHz < F0 ≤ 54MHz	Fundamental	30

**FREQ. STABILITY vs. TEMP. RANGE (Table 2)**

Temp. °C	ppm				
	±10	±15	±20	±30	±50
-10 ~ 60	○	○	○	○	○
-20 ~ 70	○	○	○	○	○
-40 ~ 85	X	△	○	○	○
-40 ~ 105	X	X	△	○	○
-40 ~ 125	X	X	X	X	○

○: Available △: Conditional X: Not available